89.(New) The interconnection component, according to claim 87 wherein:

the contact tip structure comprises multiple metallic layers.

90.(New) The interconnection component, according to claim 87 wherein:

the contact tip structure is formed as part of a cantilevered interconnect structure.

91.(New) The interconnection component, according to claim 87 wherein:

the interconnection element has a relatively flexible core element and a shell on the relatively flexible core element.

92.(New) The interconnection component, according to claim 87 wherein:

the interconnection element has a relatively flexible core and a layer, on the core element, comprising a material selected from the group consisting of nickel, an alloy of nickel, cobalt, an alloy of cobalt, and an alloy of nickel and cobalt.

93.(New) The interconnection component, according to claim 92 wherein:

the core element comprises gold.

94.(New) The interconnection component, according to claim 87 wherein:

the resilient elongate element has a core element and a shell;

the core element is readily-shaped and comprises a material selected from the group consisting of:

(a) gold, aluminum and copper with small amounts of beryllium, cadmium, silicon and magnesium, and

(b) metals of the platinum group, and

(c) lead, tin, and indium.

95.(New) The interconnection component according to claim 87 wherein: the core element has a diameter in the range of from 0.25 to 10 mils.

96.(New) The interconnection component, according to claim 87 wherein: the core element has a diameter in the range of from 0.5 to 3 mils.

97.(New) The interconnection component, according to claim 87 wherein: the core element has a length in the range of from 10 mils to 500 mils.

98.(New) The interconnection component, according to claim 87 wherein: the shell has at least one layer which comprises a material which is selected for its ability to provide mechanical properties selected from the group consisting of spring properties, resiliency yield strength and compliance for the resilient elongate element.

99.(New) The interconnection component, according to claim 98 wherein: the shell has at least one layer which comprises a material which has a yield strength of at least thirty thousand pounds per square inch.

100.(New) The interconnection component, according to claim 98 wherein: the shell has at least one layer which comprises a material which has a tensile strength in excess of 80,000 pounds per square inch.

101.(New) The interconnection component, according to claim 87 wherein: the shell has at least one layer which comprises a material selected from the group consisting of nickel, iron, and cobalt.

102.(New) The interconnection component, according to claim 87 wherein:

the shell has at least one layer which comprises a material selected from the group consisting of copper, nickel, cobalt, tin, boron, phosphorous, chromium, tungsten, molybdenum, bismuth, indium, cesium, antimony, gold, silver, rhodium, palladium, platinum, lead, and ruthenium.

103.(New) The interconnection component, according to claim 87 wherein:

the core element comprises gold and the shell comprises a material selected from the group consisting of nickel and cobalt.

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104.(New) The interconnection component, according to claim 91 wherein:

the shell has a thickness in the range of from 0.20 mils to 20 mils.

105.(New) The interconnection component, according to claim 91 wherein:

the shell has a thickness in the range of from 0.25 to 10 mils.

106.(New) An electronics assembly comprising:

a substrate;

a resilient elongate element having a first end secured to the substrate; and

a contact tip structure secured to a second end of the resilient elongate element opposing the first end.

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107.(New) The electronics assembly, according to claim 106 further comprising:

a plurality of resilient elongate elements, each having a first end secured to the substrate; and

a plurality of contact tip structures, each secured to a respective end of the respective resilient elongate element opposing a respective first end thereof.

108.(New) The electronics assembly, according to claim 106 wherein:

the contact tip structure is separately fabricated and mounted to the resilient elongate element.

109.(New) The electronic assembly, according to claim 108 wherein:

the resilient elongate element has a relatively flexible core element and a layer on the relatively flexible core element.

110.(New) The electronic assembly, according to claim 108 wherein:

the resilient elongate element has a relatively flexible core and a layer, on the relatively flexible core element, of a material selected from the group consisting of nickel, an alloy of nickel, cobalt, an alloy of cobalt and an alloy of nickel and cobalt.

111.(New) The electronic assembly, according to claim 110 wherein:

the relatively flexible core element comprises gold.

112.(New) The electronics assembly, according to claim 106 wherein:

the resilient elongate element has a core element and a shell;

the core element is readily-shaped and comprises a material selected from the group consisting of:

(a) gold, aluminum and copper with small amounts of beryllium, cadmium, silicon and magnesium, and

(b) metals of the platinum group, and

(c) lead, tin, and indium.

113.(New) The electronics assembly, according to claim 109 wherein:

the layer comprises a material which is selected for its ability to provide mechanical properties selected from the group consisting of spring properties, resiliency yield strength and compliance for the resilient elongate element.

114.(New) The electronics assembly, according to claim 109 wherein:

the first end of the relatively flexible core element forms a first intimate bond with a conductive contact terminal carried by an electronic component; and

the layer forms a second intimate bond with at least a portion of the conductive contact terminal immediately adjacent the first intimate bond.